



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Flanged Termination 20 Watts, 50Ω



General Specifications

Resistive Element	Thick film
Substrate	Beryllium oxide ceramic
Cover	Alumina Ceramic
Mounting flange	Copper, nickel plated per QQ-N-290
Leads	99% pure silver (.005" thick)

Features:

- DC – 6.0 GHz
- 20 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Electrical Specifications

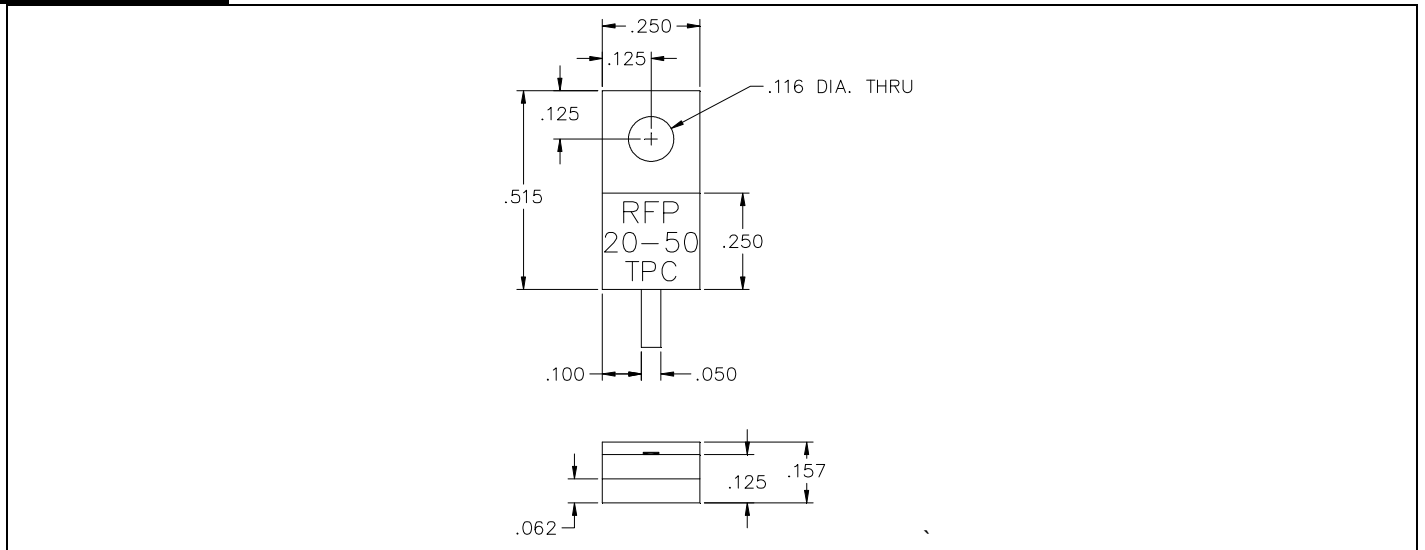
Resistance Range:	50 ohms, $\pm 5\%$
Frequency Range;	DC – 6.0 GHz
Power:	20 Watts
VSWR	1.25:1 DC – 6.0 GHz

Note: Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. Operating temperature is -55°C to 150°C (see chart for derating temperatures).

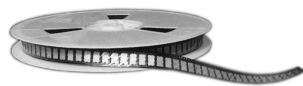
All dimensions in inches.

Specifications subject to change with out notice.

Outline Drawing

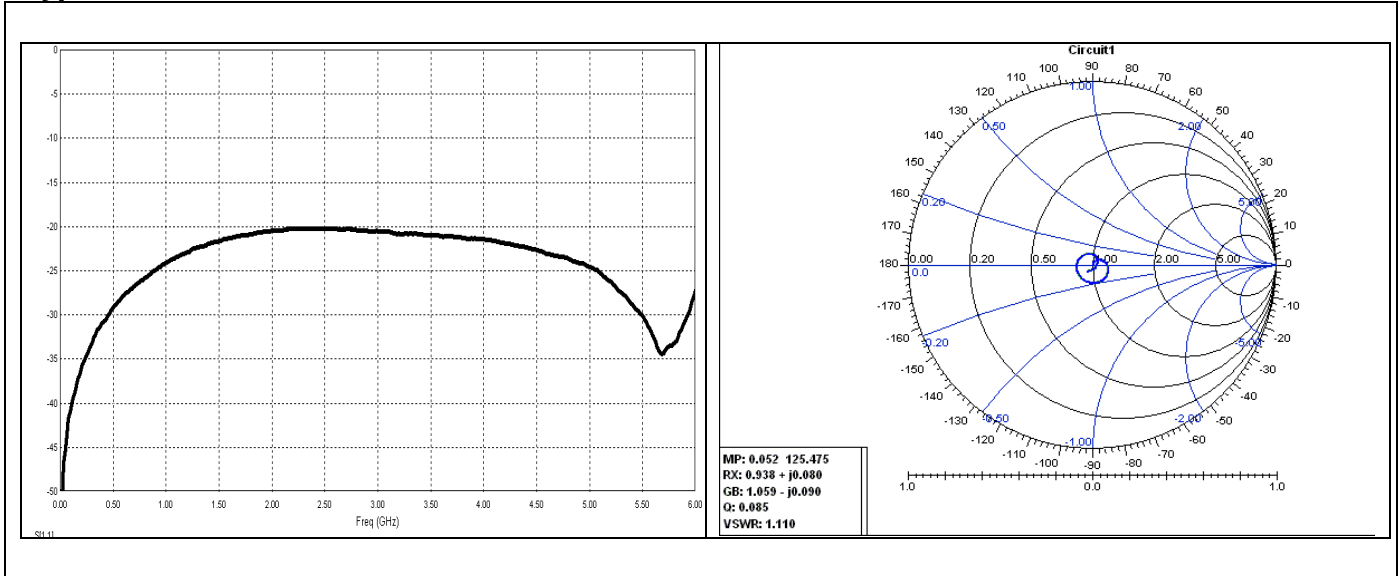


20-50TPC (097) Rev A

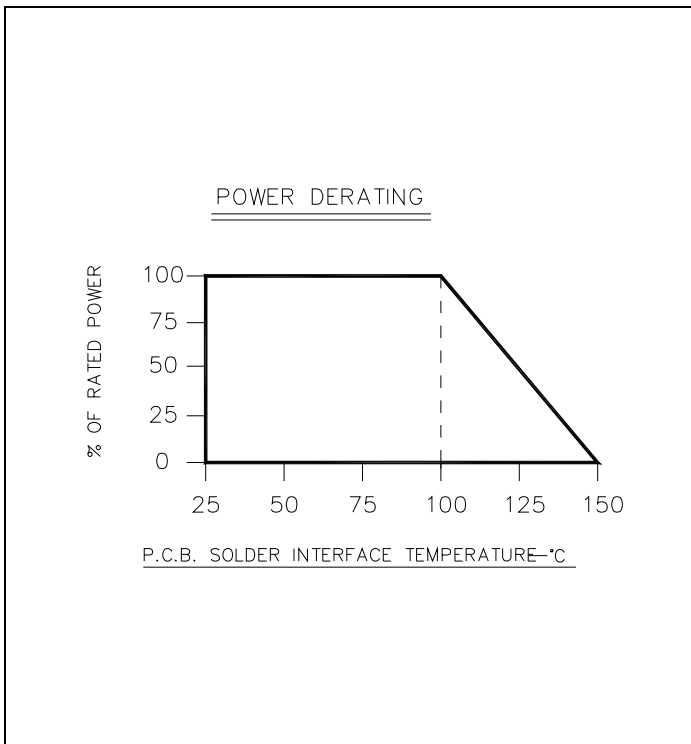




Typical Performance:



Power De-rating:



Mounting Footprint and Procedure:

The diagrams show two methods for mounting the device on a PCB. The left diagram, labeled 'SUGGESTED STRESS RELIEF METHODS', shows two cases: 'BOARD LOWER THAN LEAD' and 'BOARD EVEN WITH LEAD'. The right diagram, labeled 'NOT RECOMMENDED APPLICATION', shows two cases: 'BOARD LOWER THAN LEAD' and 'BOARD HIGHER THAN LEAD'. A dimension of .025 MIN. (2 PLACES) is indicated for the lead length. The scale for both diagrams is NONE.

SUGGESTED MOUNTING PROCEDURES:

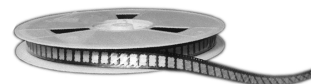
1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING APPROPRIATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

** FOR MORE DETAILS CONTACT FACTORY **

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Available on Tape and Reel For Pick and Place Manufacturing.



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